

The Most Accurate Manual Scribing System Available Handy Wafer Scriber



Features

- Suitable for scribing InP, Glass, GaAs, Si, SiO₂, Sapphire and SiC wafers up to 3 inches in diameter
- Predetermined scribing angle for optimal results
- Select tool. Secure wafer and scribe
- Two-part design with non-slip surface holds wafers firmly while scribing
- Unique pen design enables uniform scribing pressure

Instructions

1 Assemble

2 Sandwich wafer between plates

Wafer

3 Scribe the wafer along the guide

Scan QR code for more info
(Link to 1min video)

TECDIA Diamond Scribing Tools



Wafer Scribing Tools

Benefits

- 1 Best in Class Tool**
 Each tool is meticulously crafted and inspected to only the highest standards for shank uniformity, diamond positioning and cutting angles.
- 2 High Yield Potential**
 Our standard shank is designed to work with most commercially available scribing platforms. Although not recommended for best performance, our tools can be used in hand scribing applications.
- 3 Design**
 Tecdia scribe tools are designed for longevity and maximum wafer singulation yield. Diamonds are bonded to the shank through a proprietary method that yields extremely accurate alignment geometries.
- 4 Custom Tools**
 Custom designed tools available based on your applications and specific needs to produce the optimal results.



Selection Guide

	4 points	3 points	2 points
SiC GaN Sapphire		TD-3YP	TD-2P
Si GaAs InP	TD-4PSS		
ZnO	TD-410		



4 point tools – medium width scribe lines for a wide range of materials and thicknesses. Ideal for applications requiring scribe quality.

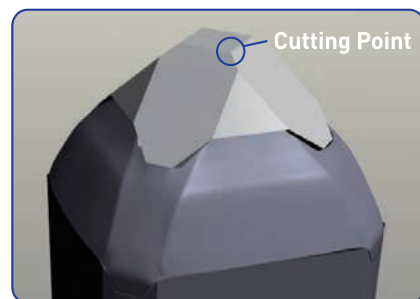


3 point tools – wide scribe lines suited for “thick and hard” wafer materials. It has the most scribe strength.



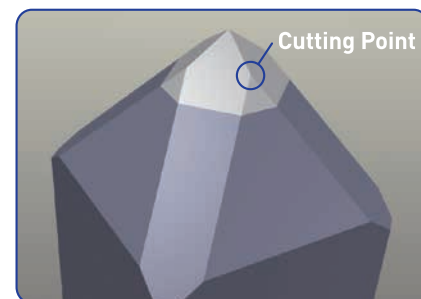
2 point tools – narrow scribe lines best for trench scribing applications.

Lineup



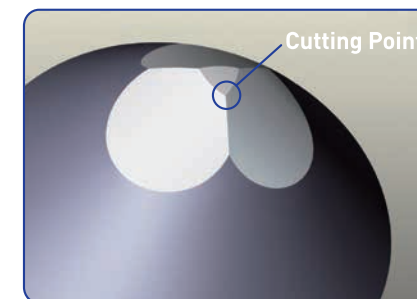
4 Point Tool (Toe)
P/N: TD-4PSS

- Number of cut points: 4
- Ridge line angle: 35°
- Recommended scribing angle: 56° to 65°
- Characteristics: With the cutting point at the tip, toe point tools yield a sharp and narrow scribe line which is ideal for softer wafer materials that only require minimal scribing pressure.



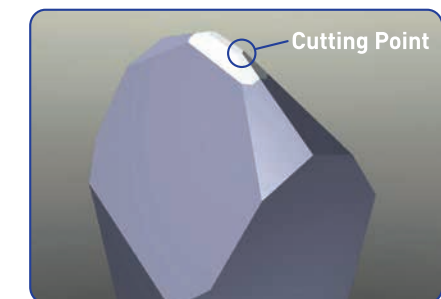
4 Point Tool (Heel)
P/N: TD-410, TD-420

- Number of cut points: 4
- Ridge line angle: 35°
- Recommended scribing angle: 52° to 55°
- Characteristics: Unlike the toe point, the triangular heel point has a wide cut line making it ideal for thicker and softer materials which also helps to reduce chipping.



3 Point Tool (Toe)
P/N: TD-3YP

- Number of cut points: 3
- Ridge line angle: 22.5°
- Recommended scribing angle: 68° to 72°
- Characteristics: The curved ridges surrounding the cutting point allow for maximum downward force yielding a wide and deep scribe line. This tool type is commonly used for hard and thick wafer materials.



2 Point Tool (Toe)
P/N: TD-2P

- Number of scribing points: 2
- Ridge line angle: 35°
- Recommended scribing angle: 56 to 65°
- Characteristics: A sharp and narrow cut point allows for scribing deep trench, bump or mesa structures without touching the trench edges. The cutting point is similar to 4 point toe tools but much thinner for clearance.